

**METHODS AND APPARATUS FOR THE DETECTION OF DAMAGED
REGIONS ON DIELECTRIC FILM OR OTHER PORTIONS OF A DIE**

Abstract

Techniques for detecting damage on an integrated circuit die using a particle suspension
5 solution are disclosed. The particles of the suspension solution preferentially attach to damaged
regions on exposed dielectric films or other portions of the die. For example, one aspect of the
invention is a method of detecting damage to a dielectric film used in fabricating a die of an
integrated circuit. A particle suspension solution is applied to the die and damaged regions of the
dielectric film are identified as areas having an accumulation of particles of the particle suspension
10 solution.